

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions,
and listings of claims in the application:

LISTING OF CLAIMS:

1. (canceled)

2. (currently amended) The smart card according
to claim 1 21, wherein the subassembly further includes an
interface component (3) connected between the microcircuit (1)
and the accessible component (2).

3. (previously presented) The smart card according
to claim 2, wherein the interface component is a controller for
the accessible component.

4. (currently amended) The smart card according to
claim 1 21, wherein the connections within the subassembly are
made by connecting wires (7, 8, 9).

5. (previously presented) The smart card according
to claim 4, wherein each connecting wire is connected, firstly,
to the microcircuit (1) or to a component (2, 3), and, secondly,
to a connecting track (4, 5) carried by the support film.

6. (currently amended) The smart card according to claim ~~4~~ 21, wherein the housing includes at least one cavity (C1) in which the microcircuit (1) is fixed and one cavity (C2) in which the accessible component (2) is fixed, at least one rib (15, 16) being provided between the cavities.

7. (previously presented) The smart card according to claim 6, wherein the support film includes an area mechanically weakened in bending between at least the microcircuit and a component and adapted to bear against a rib.

8. (previously presented) The smart card according to claim 7, wherein a mechanically weakened area is formed on either side of the microcircuit and of each component.

9. (previously presented) The smart card according to claim 7, wherein each mechanically weakened area includes at least one slot (F1 to F6).

10. (previously presented) The smart card according to claim 6, wherein connecting tracks (4, 5) are formed between the microcircuit and each component, each track facing a rib and being crossed by at least one mechanically weakened area.

11. (previously presented) The smart card according to claim 6, wherein each cavity is filled with a rigid material containing the microcircuit or a component and extending as far as the support film.

12. (previously presented) The smart card according to claim 9, wherein each cavity is provided at the periphery of its bottom with at least one depression (18).

13. (canceled)

14. (currently amended) The method according to claim ~~13~~ 22, wherein a cavity (C1) for the microcircuit (1) and a cavity (C2) for the accessible component (2) are formed in the housing.

15. (previously presented) The method according to claim 14, wherein areas mechanically weakened in bending (F2, F3, F4, F5) are formed in the support film at least between the microcircuit and the accessible component.

16. (previously presented) The method according to claim 15, wherein areas mechanically weakened in bending are formed in the support film on either side of the microcircuit and of each component.

17. (previously presented) The method according to claim 15, wherein the areas mechanically weakened in bending are formed by slots (F1, ..., F6).

18. (previously presented) The method according to claim 14, wherein at least one area mechanically weakened in bending is disposed facing a rib (15, 16) formed in the housing between two cavities.

19. (previously presented) The method according to claim 14, wherein connecting tracks (4, 5) connected by wires to the microcircuit or to a component are crossed by the areas mechanically weakened in bending.

20. (previously presented) The method according to claim 14, wherein at least one depression (18) is formed at the periphery of the bottom of at least one cavity.

21. (new) A smart card comprising:
a card support with a housing formed in a portion of the thickness of said card support;

a subassembly fixed in the housing, the subassembly comprising a support film having an internal face and an external face and provided with a window, the subassembly further comprising a plurality of external contacts being provided on the external face of the support film, and a microcircuit and at least one other component both mounted on the internal face of the support film, the window being located facing the other component whereby the other component is an accessible component which is accessible on the surface of the smart card through the window.

22. (new) A method for fabricating a smart card comprising:

providing a card support and forming a housing in the card support in a portion of the thickness of the card support;

assembling a subassembly by providing a support film having an internal face and an external face and provided with a window, providing a plurality of external contacts on the external face of the support film, and mounting a microcircuit and at least one other component on the internal face of the support film, the window being located facing the other component; and

fixing the subassembly in the housing,

whereby the other component is an accessible component which is accessible on the surface of the smart card through the window.

23. (new) The smart card according to claim 21, wherein the housing comprises at least one cavity where at least a portion of the subassembly is fixed by a resin.

24. (new) The method according to claim 22, wherein the forming of a housing in the card body comprises forming at least one cavity for at least a portion of the subassembly, and wherein the fixing of the at least a portion of the subassembly in the at least one cavity is made with a resin.